

ABSTRACT

Provided is a polishing liquid composition that is able to improve the polishing rate of a silicon oxide film in one aspect.

5 An aspect of the present disclosure relates to a polishing liquid composition for a silicon oxide film. The polishing liquid composition contains cerium oxide particles (component A), an additive (component B), and an aqueous medium. The component B is a compound having a reduction potential of 0.45 V or more when a 10 ppm aqueous solution of the component B is measured by cyclic voltammetry (with an Ag/AgCl electrode as a reference).